



SP-EH3000

Technical Data Sheet

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Latent Epoxy Curative

SP-EH3000 is a latent curative for heat-activated epoxy systems. It is micronized dicyandiamide. The Chemical Abstract Number is 461-58-5. The amine hydrogen equivalent weight is 21 g/eq. Typical usage levels are 8-12 parts per hundred epoxy resin. When SP-EH3000 is used on its own to cure epoxy resin systems, the shelf life of the uncured material can be greater than 1 year. SP-EH3000 can be used with SP-AD0052 to lower the cure temperature and cure time of an epoxy system while still having a long shelf life.

Specific Physical Form:	Powder
Color:	White
Shelf Life:	1 Year

Typical Properties:

Percent Volatiles:	< 0.5%
Particle Size:	90% < 30 microns 10 micron mean
Melting Point Using DSC:	405°F - 412°F (207°C - 211°C)

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